

Features

- ESD protection for one line with bi-directional
- Provide transient protection for the protected line to
IEC 61000-4-2 (ESD) $\pm 15\text{kV}$ (air) / $\pm 9\text{kV}$ (contact)
IEC 61000-4-5 (Lightning) 3A (8/20 μs)
- **Ultra-low capacitance: 0.18pF typical**
- For low operating voltage applications: **1V and below**
- 0201 small MCSP package saves board space
- Fast turn-on and low clamping voltage
- Solid-state silicon-avalanche and active circuit triggering technology
- **Green part**

Applications

- USB4 interface
- USB Type-C interface
- PCIe Gen4 and Gen5 interfaces
- Thunderbolt interface
- Handheld portable applications
- Consumer electronics

Description

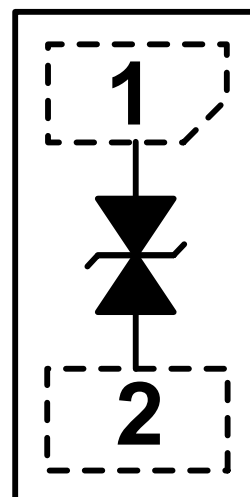
AZ5BFS-01M is a design which includes a bi-directional ESD rated clamping cell to protect high-speed data interfaces in an electronic system. The AZ5BFS-01M has been specifically designed to protect sensitive components which are connected to data and transmission lines from over-voltage caused by Electrostatic Discharging (ESD), Lightning and Cable Discharge Event (CDE).

AZ5BFS-01M is a unique design which includes proprietary clamping cell with ultra-low capacitance in a small package. During transient conditions, the proprietary clamping cell prevents over-voltage on the control/data lines, protecting any downstream components.

AZ5BFS-01M is bi-directional and may be used on lines where the signal swings above and below ground.

AZ5BFS-01M may be used to meet the ESD immunity requirements of IEC 61000-4-2, Level 4 ($\pm 15\text{kV}$ air, $\pm 8\text{kV}$ contact discharge).

Circuit Diagram / Pin Configuration



MCSP0603P2YS (Top View)

Specifications

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$, unless otherwise specified)			
Parameter	Symbol	Rating	Unit
Peak Pulse Current ($t_p = 8/20\mu\text{s}$)	I_{pp}	3	A
Operating Voltage	V_{DC}	± 1.1	V
ESD per IEC 61000-4-2 (Air)	V_{ESD-1}	± 15	kV
ESD per IEC 61000-4-2 (Contact)	V_{ESD-2}	± 9	kV
Lead Soldering Temperature	T_{SOL}	260 (10 sec.)	$^\circ\text{C}$
Operating Temperature	T_{OP}	-55 to +85	$^\circ\text{C}$
Storage Temperature	T_{STO}	-55 to +150	$^\circ\text{C}$

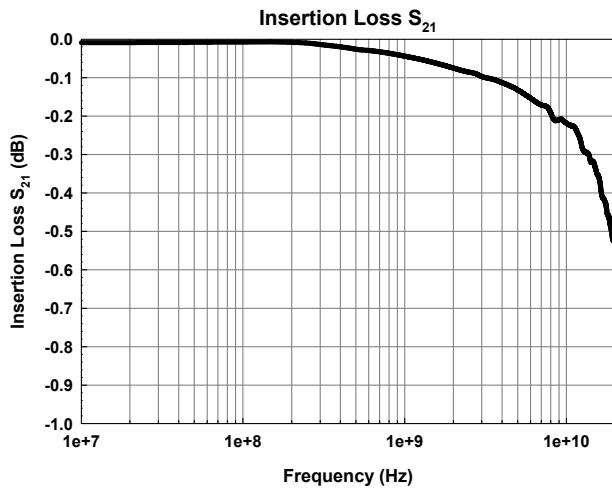
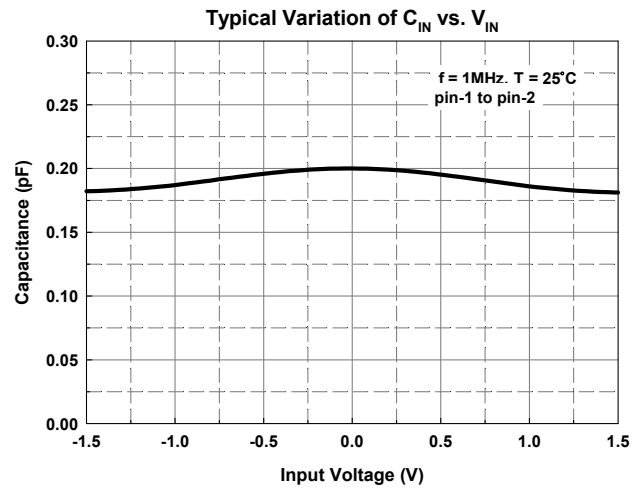
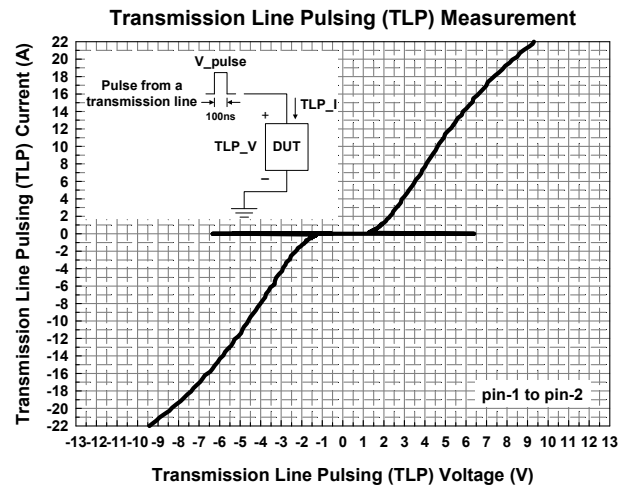
Electrical Characteristics						
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Reverse Stand-Off Voltage	V_{RWM}	$T = 25^\circ\text{C}$.	-1		1	V
Reverse Leakage Current	I_{Leak}	$V_{RWM} = \pm 1\text{V}$, $T = 25^\circ\text{C}$.			500	nA
Reverse Breakdown Voltage	V_{BV}	$I_{BV} = 10\mu\text{A}$, $T = 25^\circ\text{C}$.	2.2			V
ESD Clamping Voltage (Note 1)	V_{CL-ESD}	IEC 61000-4-2 +8kV ($I_{TLP} = 16\text{A}$), contact mode, $T = 25^\circ\text{C}$.		6.5		V
ESD Dynamic Turn on Resistance	$R_{dynamic}$	IEC 61000-4-2 0~+8kV, contact mode, $T = 25^\circ\text{C}$.		0.35		Ω
Channel Input Capacitance	C_{IN}	$V_R = 1\text{V}$, $f = 1\text{MHz}$, $T = 25^\circ\text{C}$.		0.18		pF
Insertion Loss	I_L	$f = 10\text{GHz}$.		0.25		dB

Note 1: ESD Clamping Voltage was measured by Transmission Line Pulsing (TLP) System.

TLP conditions: $Z_0 = 50\Omega$, $t_p = 100\text{ns}$, $t_r = 1\text{ns}$.



Typical Characteristics



Application Information

The AZ5BFS-01M is designed to protect one line against system ESD pulse by clamping it to an acceptable reference.

The usage of the AZ5BFS-01M is shown in Fig. 1. Protected line, such as data line or control line, is connected to pin 1. The pin 2 is connected to a ground plane on the board. In order to minimize parasitic inductance in the board traces, all path lengths connected to the pins of AZ5BFS-01M should be kept as short as possible.

In order to obtain enough suppression of ESD induced transient, a good circuit board is critical. Thus, the following guidelines are recommended:

- Minimize the path length between the protected lines and the AZ5BFS-01M.
- Place the AZ5BFS-01M near the input terminals or connectors to restrict transient coupling.
- The ESD current return path to ground should be kept as short as possible.
- Use ground planes whenever possible.
- NEVER route critical signals near board edges and near the lines which the ESD transient easily injects to.

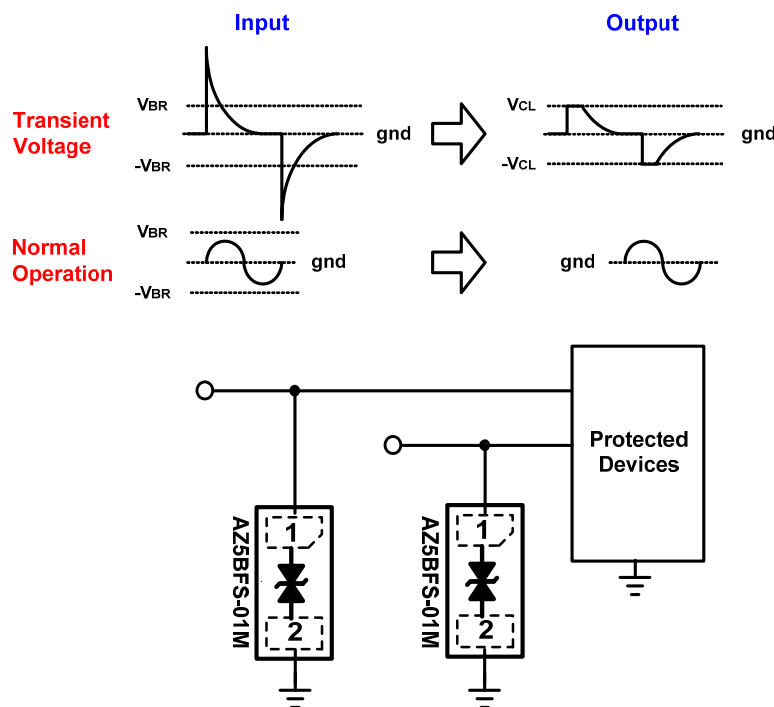
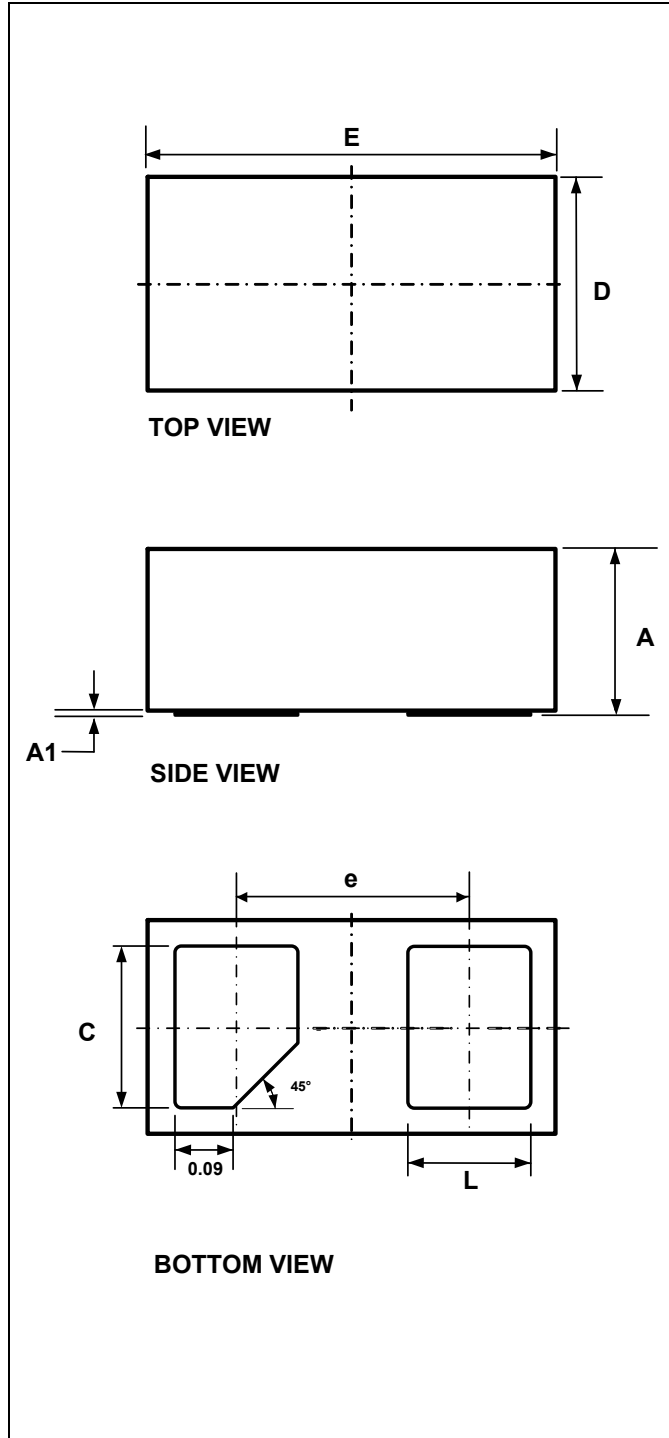


Fig. 1

Mechanical Details

MCSP0603P2YS

Package Diagrams

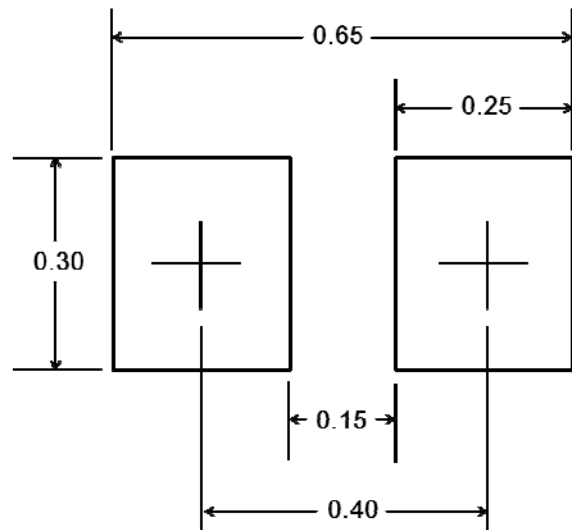


Package Dimensions

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
E	0.615	0.630	0.645
D	0.315	0.330	0.345
A	0.235	0.250	0.265
A1	0.005	0.015	0.050
L	0.170	0.190	0.210
C	0.230	0.250	0.270
e	0.360 BSC		

Land Layout

Unit: mm

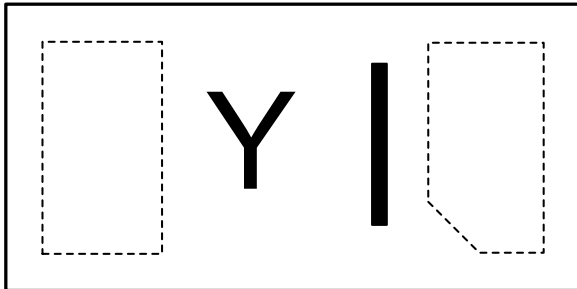


Notes:

This LAND LAYOUT is for reference purposes only. Please consult your manufacturing partners to ensure your company's PCB design guidelines are met.



Marking Code



Y= Device Code

Part Number	Marking Code
AZ5BFS-01M.R7G (Green Part)	Y

Note : Green means Pb-free, RoHS, and Halogen free compliant.

Ordering Information

PN#	Material	Type	Reel size	MOQ	MOQ/internal box	MOQ/carton
AZ5BFS-01M.R7G	Green	T/R	7 inch	15,000/reel	4 reels = 60,000/box	6 boxes = 360,000/carton

Revision History

Revision	Modification Description
Revision 2024/06/25	Preliminary Release.
Revision 2025/02/11	Formal Release.